ABSTRACT OF THE DISCLOSURE

To improve the connection reliability at the time of packaging a semiconductor device and to make the method management easy in a semiconductor device manufacturing method.

The semiconductor device comprises: a tub 1e for supporting a semiconductor chip 2; a sealing body 3 formed by sealing the semiconductor chip 2 with a resin; a plurality of leads 1a made of a copper alloy, exposed to the back face 3a of the sealing body 3, and having a soldered layer 8 on the exposed mounted face 1d; and wires 4 for connecting the pads 2a of the semiconductor chip 2 and the corresponding leads 1a. In the manufacture method, the sealing body 3 is polished, after resin-molded, at its back face 3a with a brush to form the two widthwise edge portions, as exposed from the back face 3a of the sealing body 3, of the lead 1a into rounded faces, and the mounted face 1d of the lead 1a including the rounded faces is protruded at its central portion from the back face 3a of the sealing body 3 thereby to improve the connection reliability at the packaging time.